



Description

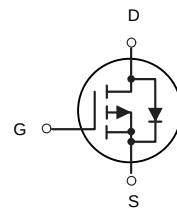
The HSTD46P4LLF6 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



General Features

$V_{DS} = -40V$ $I_D = -50A$

$R_{DS(ON)} < 13\ m\Omega$ @ $V_{GS}=10V$



P-Channel MOSFET

Application

Battery protection

Load switch

Uninterruptible power supply

Ordering Information

Product ID	Pack	Brand	Qty(PCS)
HSTD46P4LLF6	TO252-2L	HXY MOSFET	2500

Absolute Maximum Ratings ($T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-40	V
VGS	Gate-Source Voltage	± 20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, V_{GS} @ 10V ¹	-50	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, V_{GS} @ 10V ¹	-31	A
IDM	Pulsed Drain Current ²	-200	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation ⁴	55	W
TSTG	Storage Temperature Range	-55 to 150	$^{\circ}C$
T _J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$
R _{θJA}	Thermal Resistance Junction-ambient ¹	61	$^{\circ}C/W$
R _{θJC}	Thermal Resistance Junction-Case ¹	2.27	$^{\circ}C/W$



Electrical Characteristics ($T_J = 25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-40	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA
Zero Gate Voltage Drain Current	$T_J = 25^{\circ}\text{C}$	$V_{DS} = -40V, V_{GS} = 0V$	-	-	1	μA
	$T_J = 100^{\circ}\text{C}$		-	-	5	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-1.6	-2.5	V
Drain-Source On-Resistance ⁴	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -16A$	-	10.5	13	m Ω
		$V_{GS} = -4.5V, I_D = -12A$	-	14.2	20	
Forward Transconductance ⁴	g_{fs}	$V_{DS} = -10V, I_D = -16A$	-	44	-	S
Input Capacitance	C_{iss}	$V_{DS} = -20V, V_{GS} = 0V, f = 1MHz$	-	3050	-	pF
Output Capacitance	C_{oss}		-	282	-	
Reverse Transfer Capacitance	C_{rss}		-	230	-	
Gate Resistance	R_g	$f = 1MHz$	-	9	-	Ω
Total Gate Charge	Q_g	$V_{GS} = -10V, V_{DS} = -20V, I_D = -16A$	-	28	-	nC
Gate-Source Charge	Q_{gs}		-	8	-	
Gate-Drain Charge	Q_{gd}		-	8.5	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = -10V, V_{DD} = -15V, R_G = 3\Omega, I_D = -16A$	-	38	-	ns
Rise Time	t_r		-	31	-	
Turn-off Delay Time	$t_{d(off)}$		-	90	-	
Fall Time	t_f		-	9.2	-	
Diode Forward Voltage ⁴	V_{SD}	$I_S = -1A, V_{GS} = 0V$	-	-	-1.2	V
Continuous Source Current	$T_C = 25^{\circ}\text{C}$	I_S	-	-	-50	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)} = 150^{\circ}\text{C}$.
2. The EAS data shows Max. rating . The test condition is $V_{DD} = -25V, V_{GS} = -10V, L = 0.1mH, I_{AS} = -40A$.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
5. This value is guaranteed by design hence it is not included in the production test..



Typical Characteristics

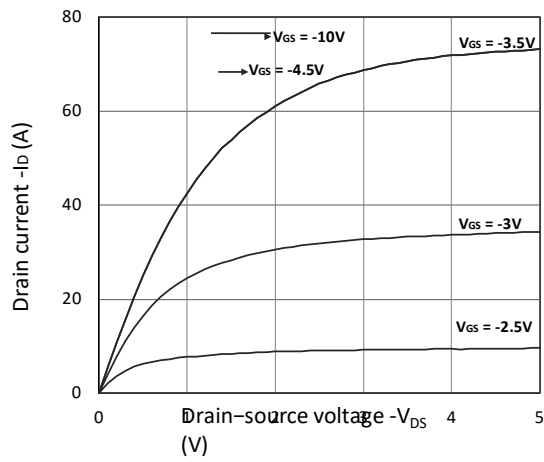


Figure 1. Output Characteristics

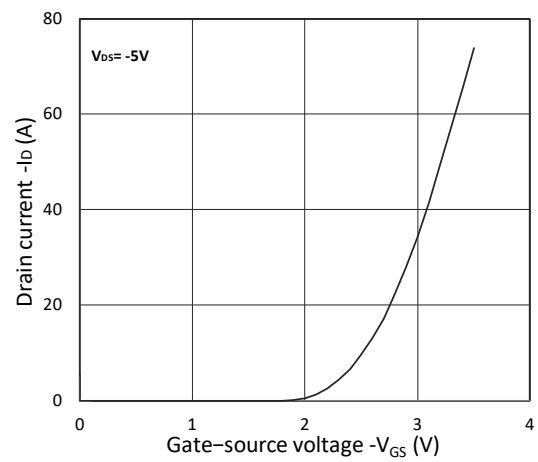


Figure 2. Transfer Characteristics

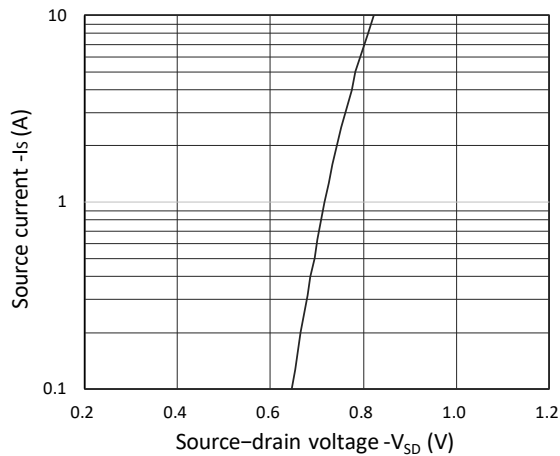


Figure 3. Forward Characteristics of Reverse

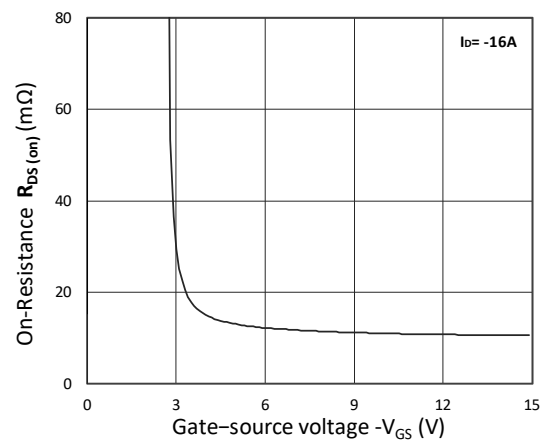


Figure 4. $R_{DS(on)}$ vs. V_{GS}

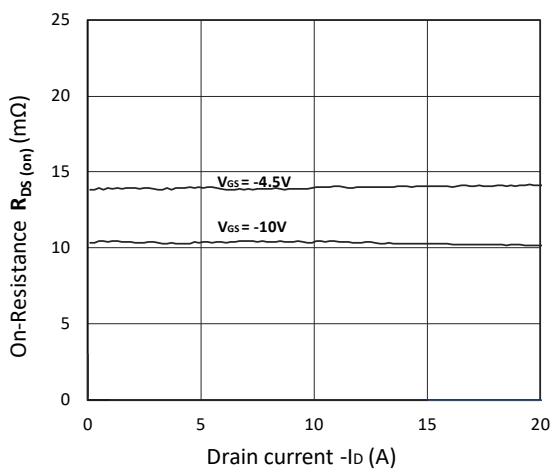


Figure 5. $R_{DS(on)}$ vs. I_D

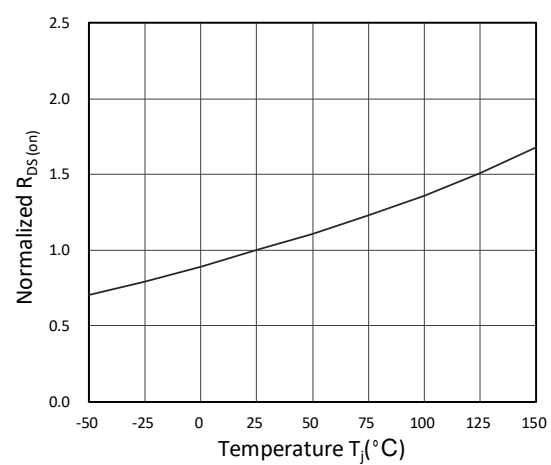


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

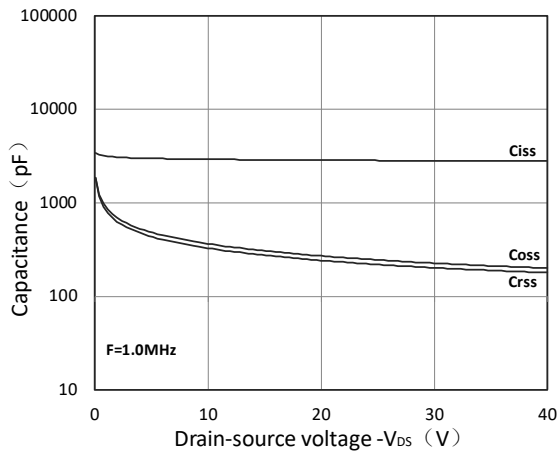


Figure 7. Capacitance Characteristics

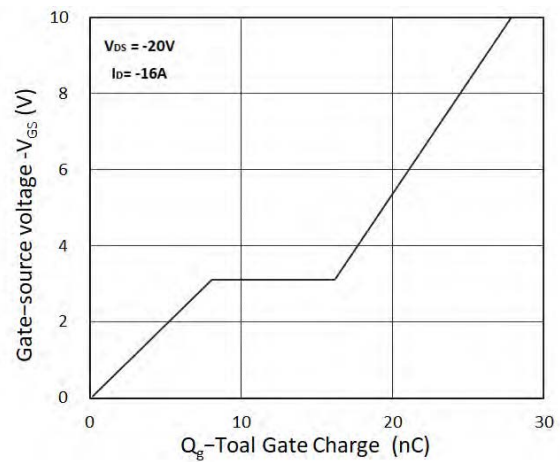


Figure 8. Gate Charge Characteristics

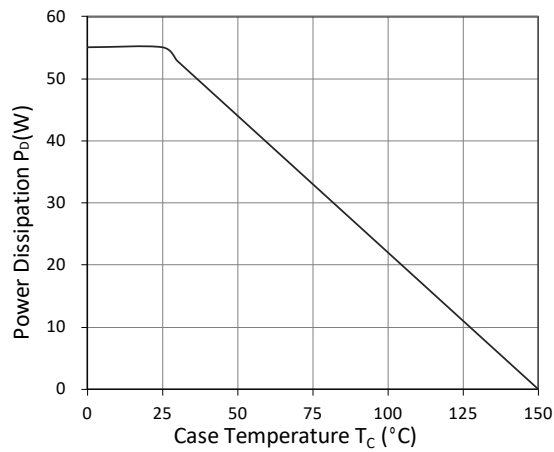


Figure 9. Power Dissipation

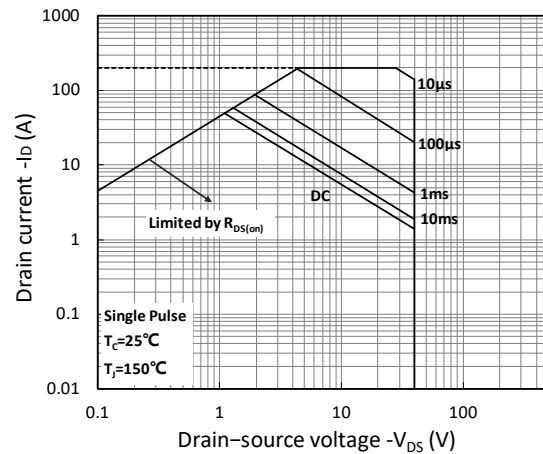


Figure 10. Safe Operating Area

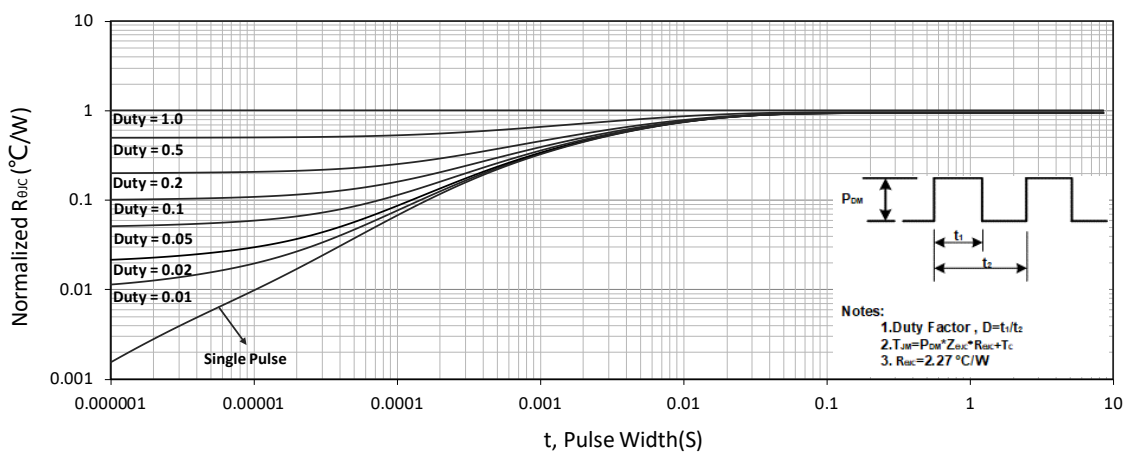


Figure 11. Normalized Maximum Transient Thermal Impedance



Test Circuit

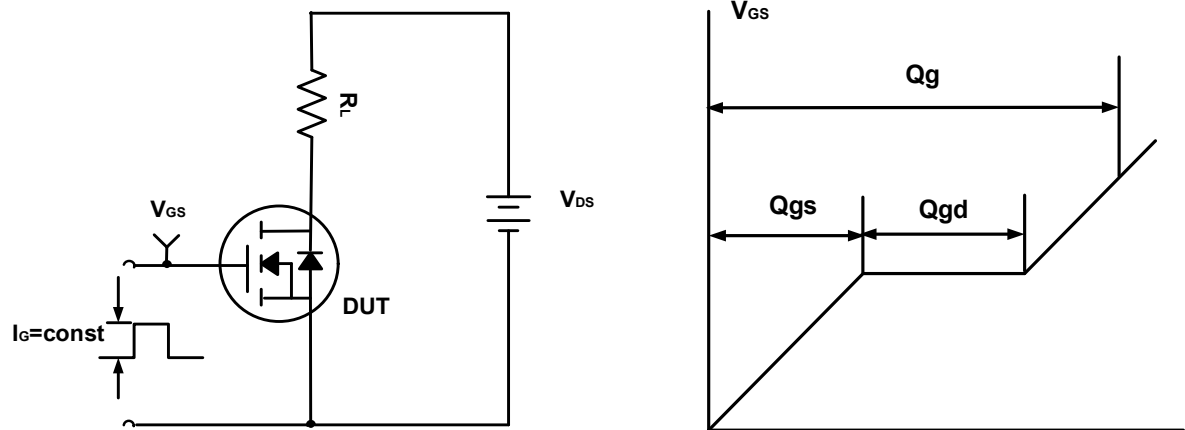


Figure A. Gate Charge Test Circuit & Waveforms

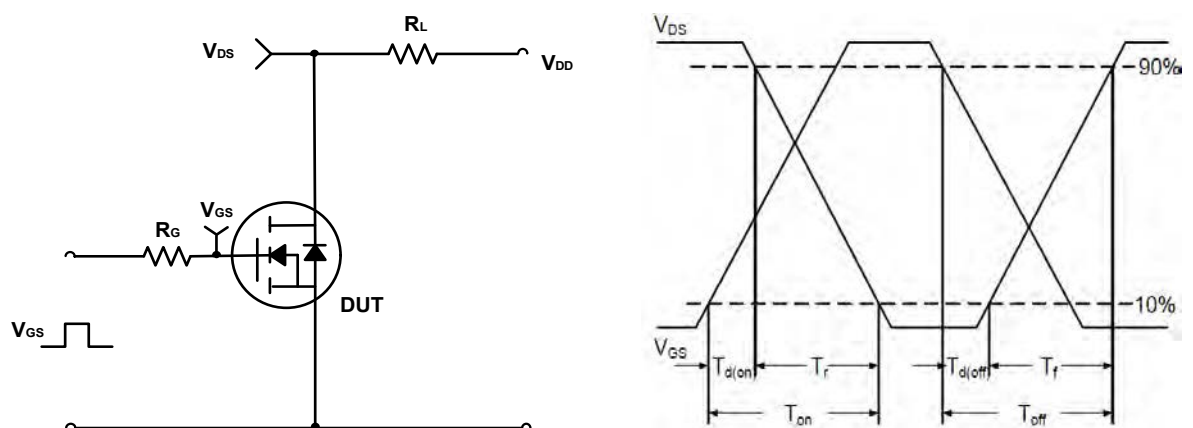


Figure B. Switching Test Circuit & Waveforms

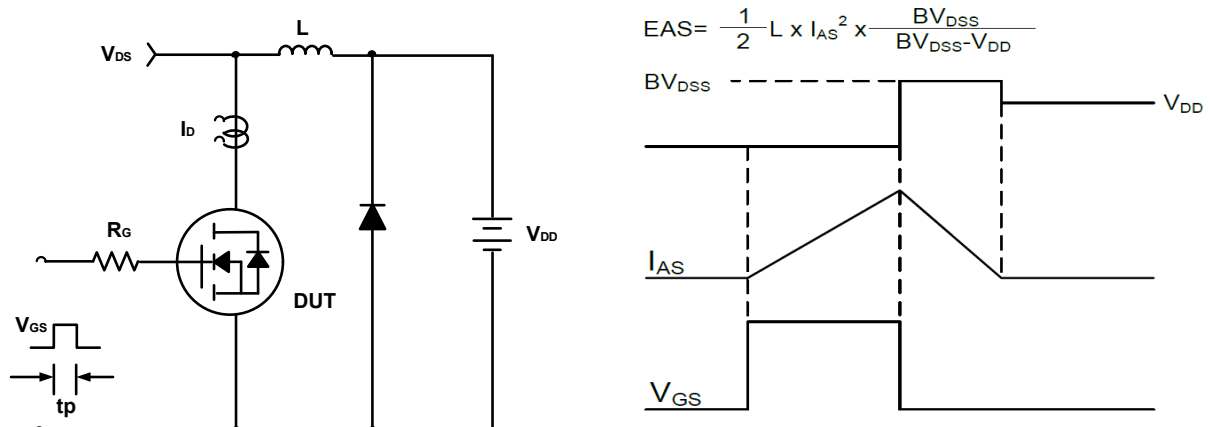
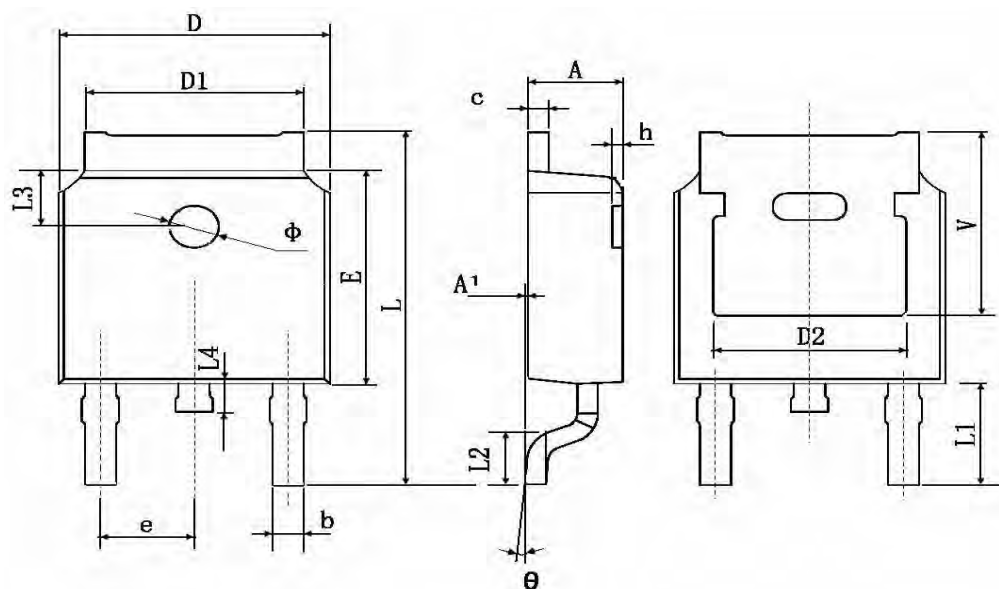


Figure C. Unclamped Inductive Switching Circuit & Waveforms



TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	



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